

ElectraJet® EMJII0 Inkjet Soldermask



ElectraJet® EMJII0 is the market-leading inkjet soldermask, delivering unmatched quality, robustness and reliability. Designed for modern PCB production, EMJI 10 provides a streamlined, sustainable, and cost-effective solution for high-performance applications.

Available in Four Vibrant Colours:

We Also Offer Flexible Soldermask:

- Green Black
- Blue
- Red







• Green

Amber

Key Features/Highlights

High Performance

- EMITIO designed to meet all key performance criteria - IPC SM840, UL-94 V-0, no SVHCs, thermal cycling and heat storage
- **Robust Formulation**
- · Ink stable under a range of temperatures and environmental conditions
- No change in ink viscosity or particle size during use or shelf life of product
- · Ink robustness critical for ensuring consistent printing with minimal problems
- Approved for use on leading inkjet printheads:
 - Konica Minolta KMI024iMHE
 - Konica Minolta KMI024iSHE
 - Konica Minolta KM1800i
 - FUJIFILM Dimatix Samba®

Reliability

- · Waveform designed to reduce print quality defects
- · Formulated to ensure high reliability jetting
- · Minimal tool downtime during operation



Why Choose Electralet® EM|| 10?

- Proven Production Formulation Commercialised since 2019, extensively validated in real-world manufacturing.
- Market Leader Electra is the global leader in inkjet soldermask, trusted by top PCB manufacturers worldwide.
- Largest supplier Largest supplier of inkjet soldermask globally.
- High-Performance & Reliable -Meets strict automotive specifications, including high-temperature storage and thermal cycling.
- Culmination of over 10 years of Innovation – Developed through a decade of dedicated R&D in inkjet soldermask technology.
- Eco-Friendly Solution Supports sustainable PCB manufacturing with reduced waste and material efficiency.



ElectraJet® EMJI 10 Inkjet Soldermask Performance

Industry Standards/Qualifications

Standard	Requirement	Result
IPC SM-840 E	CLASS T & H	Pass
UL94	V-0	Pass

Additional Final Properties

Test	Requirement	Result
Lead-Free Solder Resistance	3 x 10s at 288°C – tape test	Pass
Multiple Assembly Reflow	6 reflow cycles (peak 260°C) – no cracking	Pass
Solvent Resistance	30 seconds methylene chloride	Pass
ENIG Plating Resistance	Ni 5-10 microns, Au <0.1 microns – tape test	Pass
Acid Resistance	10% HCl, 30 min dip at 20°C – tape test	Pass
Alkali Resistance	10% NaOH, 30 min dip at 20°C – tape test	Pass
Adhesion To Gold	Cross-hatch & tape test ≥4B (ASTM) ≥GTI (ISO)	Pass
Thermal Storage DIN IEC 60068-2-2	TC7 1000h at 150°C	Pass
Thermal Shock Bosch TC7	-40°C, I50°C, I000 cycles	Pass (formulation dependent)
Thermal Shock Bosch TC4.2	-40°C, 125°C, 1000 cycles	Pass
Thermal Shock IPC-TM-650 Method 2.6.7.3	-65°C, 125°C, 100 cycles	Pass
Dielectric Constant	Measured at 10GHz, 22°C	2.99-3.50 (formulation dependent)
Dissipation Factor	Measured at 10GHz, 22°C	0.0228
Heat/Humidity	1000 hours 85°C/85%RH	Pass
Pressure Cooker (PCT)	100 min at 121°C (2 atm) – tape test	Pass
Flexibility Test Polyimide Substrate	180° crease – tape test (formulation specific)	Pass (formulation dependent)

Soldermask Outgassing

Test	ASTM E595 Requirement	Result
Total Mass Loss (TML)	Max 1.0%	0.70%
Collected Volatile Condensable Material (CVCM)	Max 0.10%	<0.01%
Recovered Mass Loss (RML) TML-WVR	Report	0.49%
Water Vapour Recovered (WVR)	Report	0.21%

